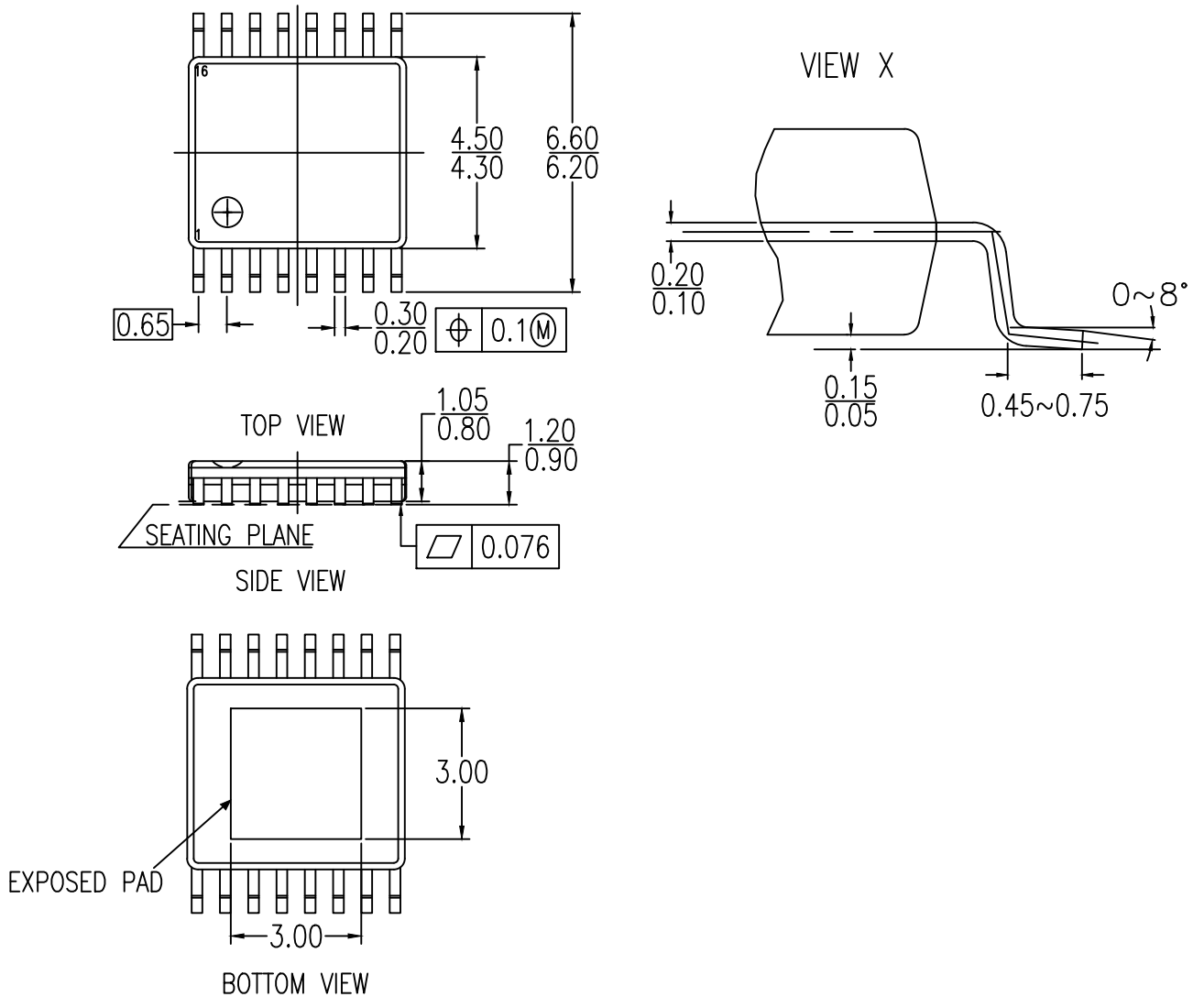


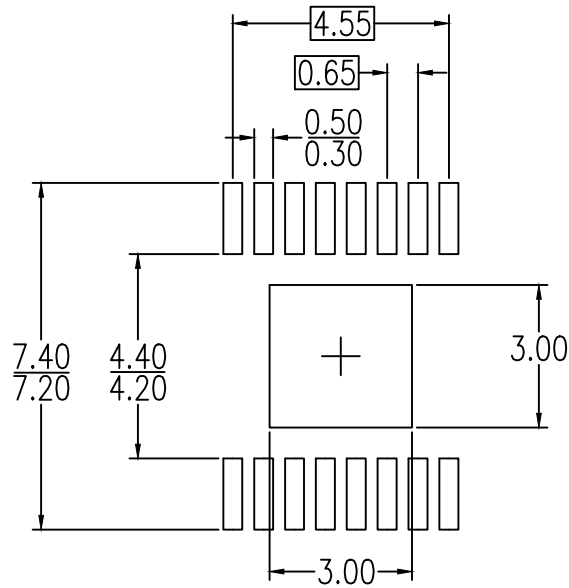
BASED ON JEDEC JEP95: MO-153

1. DIMENSIONS



2. WEIGHT ≤ 0.05 g
3. BODY MATERIAL LOW STRESS EPOXY
4. LEAD MATERIAL Cu-ALLOY
5. LEAD FINISH SOLDER PLATING
6. LEAD FORM Z-BENDS

* WITHOUT MOLD FLASH
DIMENSIONS IN MILLIMETERS



LAND PATTERN DIMENSIONS

NOTE:

1. ALL DIMENSIONS ARE IN MILLIMETERS

Package Revision History		
Date Created	Rev No.	Description
Sept 20, 2018	Rev 00	Initial Release